

Edition 1.0 2017-03

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Universal Serial Bus interfaces for data and power-VIEW Part 3-1: Universal Serial Bus 3.1 Specification (Standards.iteh.ai)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ICS 29.220; 35.200 ISBN 978-2-8322-3913-1

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Part 3-1: Universal Serial Bus 3.1 Specification

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The text of this standard is based on the following documents:

CDV	Report on voting
100/2589/CDV	100/2684/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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Revision 1.0

July 26, 2013

Revision History

Revision	Comments	Issue Date
1.0	Initial release. USB 3.0	November 12, 2008
	Incorporated errata and ECNs	June 6, 2011
1.0	Initial release. USB 3.1	July 26, 2013

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Acknowledgement of Technical Contribution

Dedication

Dedicated to the memory of Brad Hosler, the impact of whose accomplishments made the Universal Serial Bus one of the most successful technology innovations of the Personal Computer era.

The authors of this specification would like to recognize the following people who participated in the USB 3.0 Bus Specification technical workgroups. We would also like to acknowledge the many others throughout the industry who provided feedback and contributed to the development of this specification.

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